



PCN# : P56CAAB
Issue Date : Jul. 15, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Oct. 13, 2015

Expected First Date Code of Changed Product :1537

Description of Change (From) :

Wafer Fabrication site subcontractor TSMC Taiwan, 8"
Bump Site: Fairchild Semiconductor South Portland
Test to DPS: Fairchild Semiconductor Penang MalaysiaTest

Description of Change (To) :

Wafer Fabrication site subcontractor SSMC, Singapore, 8" and TSMC Taiwan 8"
Bump Site: ASE and Amkor
Test to DPS: Fairchild Semiconductor Cebu Philippines and Amkor

Reason for Change:

1. Increase the wafer supply capacity and flexibility.
2. Improve supply flexibility
3. Better quality and yields through equipment and facility upgrades
 - Increase automation in handling and inspection in assembly
4. Fairchild partnerships with foundries and assembly subcontractors
 - Best manufacturing practices - access to many customers methods and practices
 - advance technology for fast ramp of future new products and technologies

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20140398	FPF2280BUCX_F130	UCBBU-012	SSMC C18BCD gen 2 Amkor T5/T3& ASE/Cebu	3

Test Description:	Condition:	Standard :	Duration:	Results:
Highly Accelerated Stress Test	110C, 85%RH, 5.5V	JESD22-A110	264 hrs	0/231
Unbiased Highly Accelerated Stress Test	110C, 85%RH,	JESD22-A118	264 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	850 cyc	0/231
HTOL	150C, 24V	JESD22-A108	1000 hrs	0/231
High Temperature storage life	150 C	JESD22-A103	1000 hrs	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20140424	FPF2488UCX	UCBBU-015	SSMC C18BCD gen 2 ASE/Cebu	1

Test Description:	Condition:	Standard :	Duration:	Results:
Highly Accelerated Stress Test	110C, 85%RH, 5.7V	JESD22-A110	264 hrs	0/77
Unbiased Highly Accelerated Stress Test	110C, 85%RH,	JESD22-A118	264 hrs	0/77
Temperature Cycle	-40C, 125C	JESD22-A104	850 cyc	0/77
HTOL	150C, 9V/4.4V	JESD22-A108	1000 hrs	0/77
High Temperature storage life	150 C	JESD22-A103	1000 hrs	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20140426	FAN53526UCX	UCBBU-015	SSMC C18BCD gen 1 Amkor T5/T3	1

Test Description:	Condition:	Standard :	Duration:	Results:
Highly Accelerated Stress Test	110C, 85%RH, 3.6V	JESD22-A110	264 hrs	0/77
Unbiased Highly Accelerated Stress Test	110C, 85%RH	JESD22-A118	264 hrs	0/77
Temperature Cycle	-40C, 125C	JESD22-A104	850 cyc	0/77
HTOL	125C, 5.0V	JESD22-A108	1000 hrs	0/77